

## Crystal plane dependence of interface states density in c- and m-plane GaN MOS capacitors

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Owing to its high breakdown electric field and high electron saturation velocity, Gallium Nitride (GaN) is ideal for devices requiring high-power and high-speed operation. In order to realize a normally-off vertical GaN Metal-Oxide-Semiconductor Field Effects Transistors (MOSFETs) for power conversion, the deposition of insulator films, which have high reliability and low interface state density ( $D_{it}$ ), is required. However, crystal plane dependence of the  $D_{it}$  of GaN MOS capacitors has not been understood. Therefore, it is necessary to understand the crystal plane dependence of  $D_{it}$  in GaN MOS structure. In this study, we investigated the  $D_{it}$  correlations of the c-plane, just m-plane, and off-cut angles of  $5^\circ$  with the [0001] (known as “c+5 degree”) m-plane GaN substrate.

The MOS capacitors were fabricated on n-type GaN epitaxial layers, which were grown on n-type c-plane, just m-plane, and c+ $5^\circ$  m-plane GaN substrates. The thickness of each epitaxial layer 4 microns. Effective donor concentration of epitaxial layers was  $2 \times 10^{16} \text{ cm}^{-3}$  from the Capacitance-Voltage ( $C$ - $V$ ) characteristics. For the gate insulator, aluminum oxide ( $\text{Al}_2\text{O}_3$ ) was deposited using Atomic Layer Deposition (ALD) at  $260^\circ\text{C}$ . The thickness of  $\text{Al}_2\text{O}_3$  was 50 nm due to the accumulation condition of the  $C$ - $V$  characteristics. After the fabrication of the gate and back electrode,  $D_{it}$  was estimated using the Hi-Lo method at 300K.

From the resulting  $C$ - $V$  characteristics of GaN MOS capacitors, it was observed that there was a decrease in the hysteresis, flat-band voltage shift, and frequency dispersion of the just m-plane and c+ $5^\circ$  m-plane GaN MOS capacitors, when compared to those of the c-plane MOS capacitors. Figure 1 shows the crystal plane dependence of  $D_{it}$  using Hi-Lo method. The  $D_{it}$  of the m-plane GaN MOS capacitors was found to be in the range  $10^{10}$ – $10^{11} \text{ cm}^{-2}\text{eV}^{-1}$ . These results indicate that the ALD- $\text{Al}_2\text{O}_3$ /m-plane GaN interface can improve the channel mobility of vertical GaN MOSFETs.

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**References** [1] T. Yamada, J. Ito, R. Asahara, K. Watanabe, M. Nozaki, T. Hosoi, T. Shimura, and H. Watanabe, Appl. Phys. Lett., **110**, pp 261603-1-5 (2017)

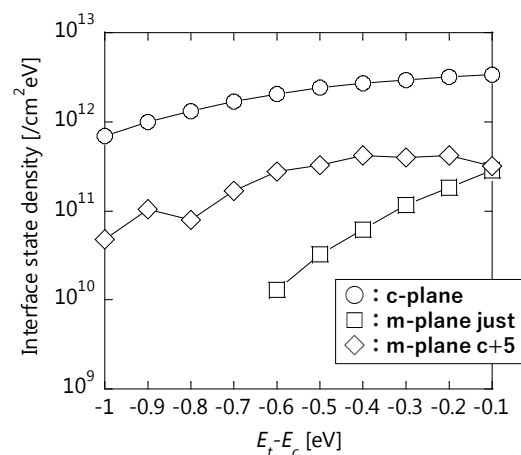


Figure 1 Interface state density of GaN MOS capacitors